



Intel® Ethernet Server Adapter X520-DA2 for Open Compute Project

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Essentials

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Product Collection	Intel® Ethernet Server Adapter X520 Series
Code Name	Products formerly Niantic
Status	Launched
Launch Date ?	Q3'13
Vertical Segment	Server
Cable Medium	Copper
Cabling Type	SFP+ Direct Attached Twin Axial Cabling up to 10m
Bracket Height	No bracket
Recommended Customer Price ?	

Supplemental Information

Product Brief	View now
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Networking Specifications

Port Configuration	Dual
Data Rate Per Port	1GbE/10GbE
Intel® Virtualization Technology for Connectivity (VT-c)	Yes
Speed & Slot Width	5.0 GT/s, x8 Lane
Controller	Intel 82599

Package Specifications



System Interface Type	PCIe v2.0 (5.0 GT/s)
Low Halogen Options Available	See MDDS

Intel® Virtualization Technology for Connectivity

On-chip QoS and Traffic Management	Yes
Flexible Port Partitioning ?	Yes
Virtual Machine Device Queues (VMDq) ?	Yes
PCI-SIG* SR-IOV Capable ?	Yes

Advanced Technologies

iWARP/RDMA ?	No
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Intel® Ethernet Power Management 	Yes
Intel® Data Direct I/O Technology 	Yes
Intelligent Offloads	Yes
Storage Over Ethernet	iSCSI, NFS

More support options for Intel® Ethernet Server Adapter X520-DA2 for Open Compute Project



Product Support



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Refer to Datasheet for formal definitions of product properties and features.

"Announced" SKUs are not yet available. Please refer to the Launch Date for market availability.

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System and Maximum TDP is based on worst case scenarios. Actual TDP may be lower if not all I/Os for chipsets are used.

Low Halogen: Applies only to brominated and chlorinated flame retardants (BFRs/CFRs) and PVC in the final product. Intel components as well as purchased components on the finished assembly meet JS-709 requirements, and the PCB / substrate meet IEC 61249-2-21 requirements. The replacement of halogenated flame retardants and/or PVC may not be better for the environment.

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